

SWITCHING
N-CHANNEL POWER MOSFET

DESCRIPTION

2SK4035 is the best switching element for the DC-DC converter usage from 24 to 48 V in the direct current input voltage. It excels in the switching characteristics in low on-state resistance and because it is the small size surface mounting externals, is the best for the high-speed switching usage of the equipment that promotes the automation of space-saving and mounting.

FEATURES

- Low input capacitance
 $C_{iss} = 74 \text{ pF TYP.}$
- Low on-state resistance
 $R_{DS(on)} = 4.5 \Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 0.25 \text{ A)}$
- Small and surface mount package (SC-96)

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK4035	SC-96 (Mini Mold Thin Type)
2SK4035-A ^{Note}	SC-96 (Mini Mold Thin Type)

Note Pb-free (This product does not contain Pb in external electrode and other parts.)

Marking: XP

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Drain to Source Voltage ($V_{GS} = 0 \text{ V}$)	V_{DSS}	250	V
Gate to Source Voltage ($V_{DS} = 0 \text{ V}$)	V_{GSS}	± 30	V
Drain Current (DC) ($T_A = 25^\circ\text{C}$)	$I_{D(DC)}$	± 0.5	A
Drain Current (pulse) ^{Note1}	$I_{D(pulse)}$	± 2.0	A
Total Power Dissipation ($T_A = 25^\circ\text{C}$)	P_{T1}	0.2	W
Total Power Dissipation ($T_A = 25^\circ\text{C}$) ^{Note2}	P_{T2}	1.25	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Notes 1. $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

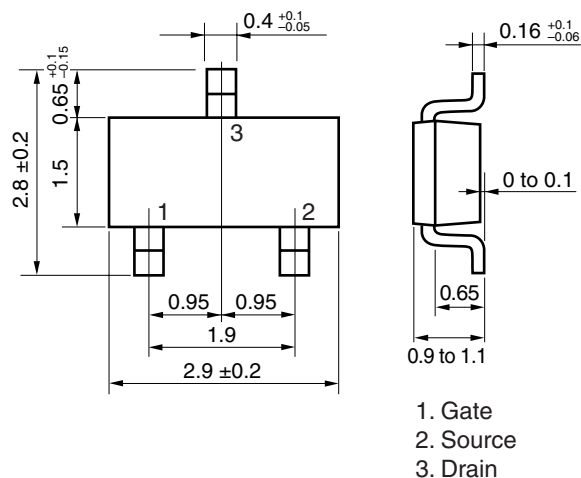
2. Mounted on FR-4 board of 50 mm x 50 mm x 1.6 mm, $t \leq 5 \text{ sec}$

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

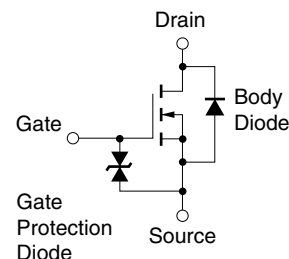
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PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT

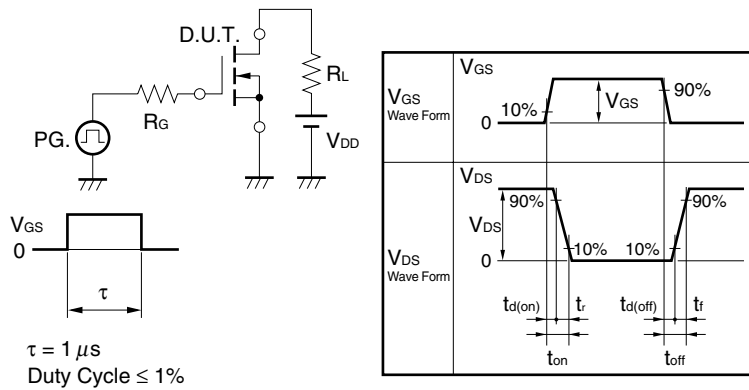


ELECTRICAL CHARACTERISTICS (TA = 25°C)

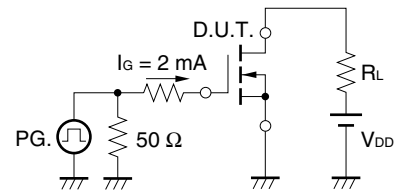
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 250\text{ V}, V_{GS} = 0\text{ V}$			10	μA
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$			± 10	μA
Gate Cut-off Voltage	$V_{GS(off)}$	$V_{DS} = 10\text{ V}, I_D = 1.0\text{ mA}$	2.5	3.5	4.5	V
Forward Transfer Admittance Note	$ y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 0.25\text{ A}$	0.2	0.5		S
Drain to Source On-state Resistance Note	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 0.25\text{ A}$		3.2	4.5	Ω
Input Capacitance	C_{iss}	$V_{DS} = 10\text{ V}$		74		pF
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$		16		pF
Reverse Transfer Capacitance	C_{rss}	$f = 1.0\text{ MHz}$		7		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 125\text{ V}, I_D = 0.25\text{ A}$		7		ns
Rise Time	t_r	$V_{GS} = 10\text{ V}$		5		ns
Turn-off Delay Time	$t_{d(off)}$	$R_G = 10\ \Omega$		12		ns
Fall Time	t_f			40		ns
Total Gate Charge	Q_G	$V_{DD} = 200\text{ V}$		4		nC
Gate to Source Charge	Q_{GS}	$V_{GS} = 10\text{ V}$		0.9		nC
Gate to Drain Charge	Q_{GD}	$I_D = 0.5\text{ A}$		2		nC
Body Diode Forward Voltage Note	$V_{F(S-D)}$	$I_F = 0.5\text{ A}, V_{GS} = 0\text{ V}$		0.84		V
Reverse Recovery Time	t_{rr}	$I_F = 0.5\text{ A}, V_{GS} = 0\text{ V}$		42		ns
Reverse Recovery Charge	Q_{rr}	$di/dt = 100\text{ A}/\mu\text{s}$		57		nC

Note Pulsed

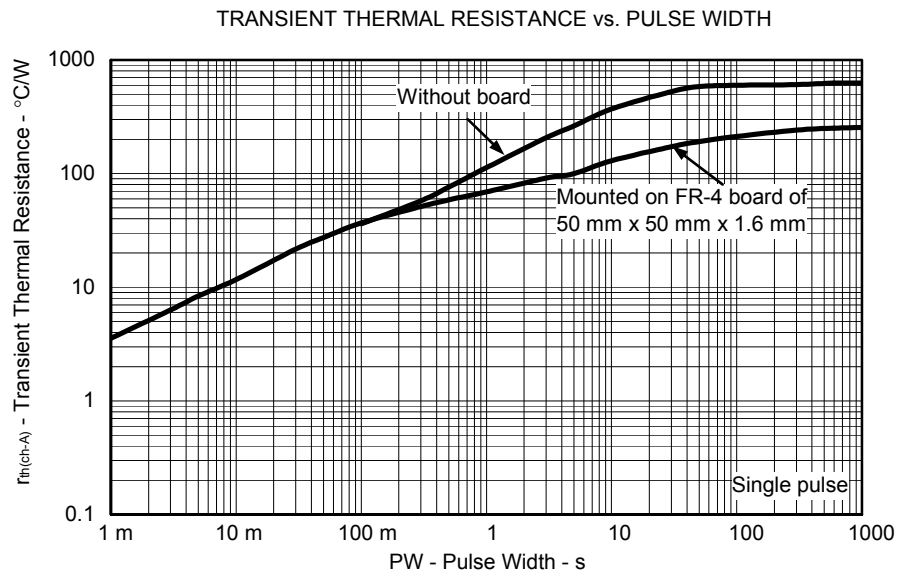
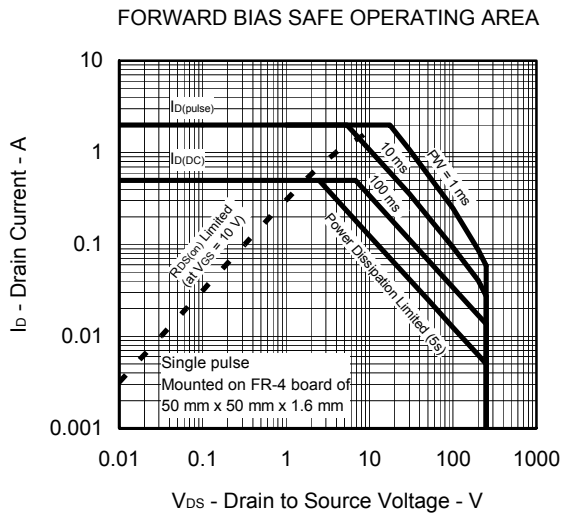
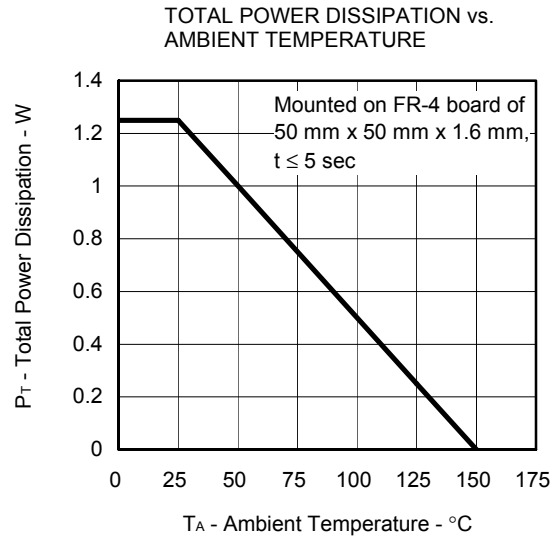
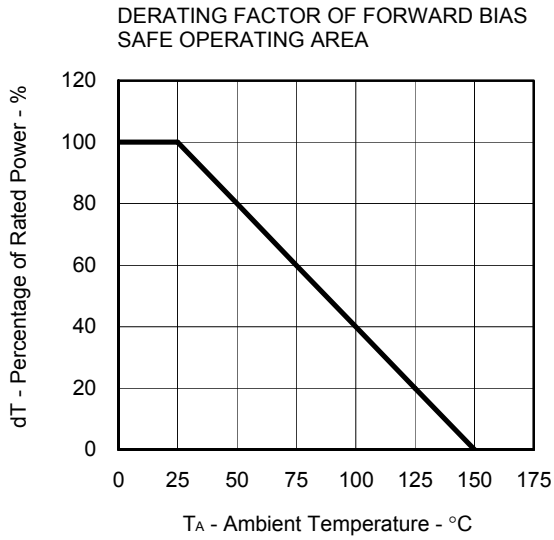
TEST CIRCUIT 1 SWITCHING TIME



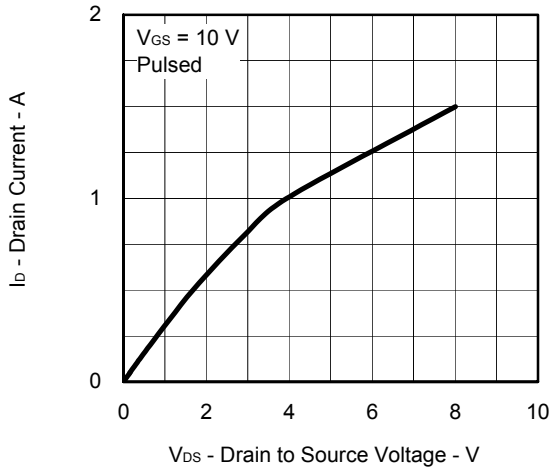
TEST CIRCUIT 2 GATE CHARGE



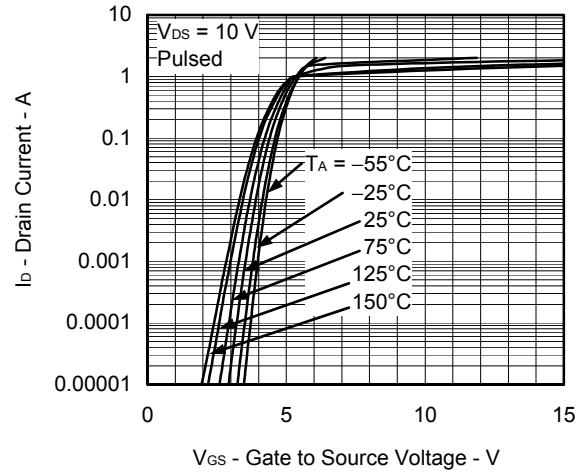
TYPICAL CHARACTERISTICS (T_A = 25°C)



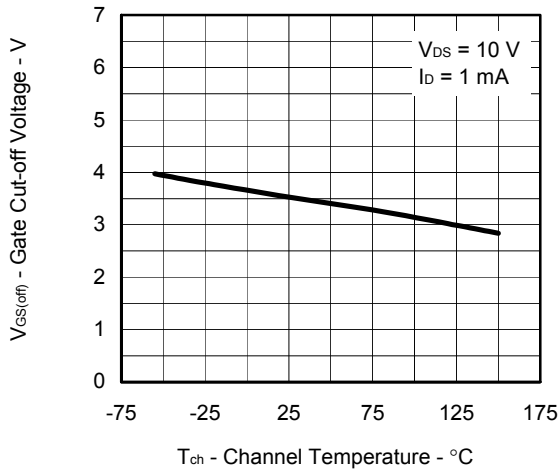
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



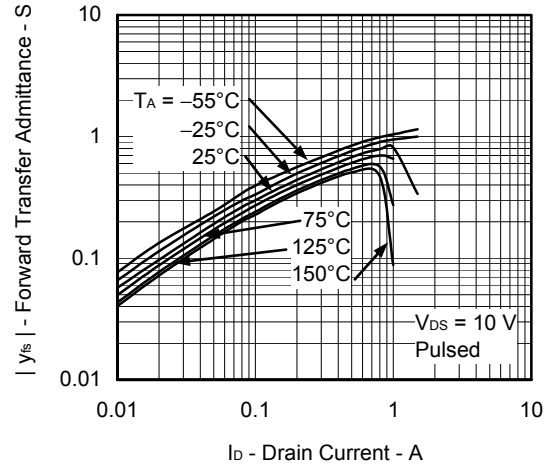
FORWARD TRANSFER CHARACTERISTICS



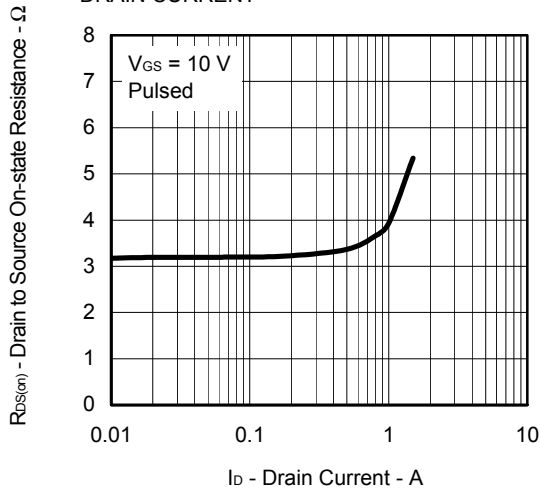
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



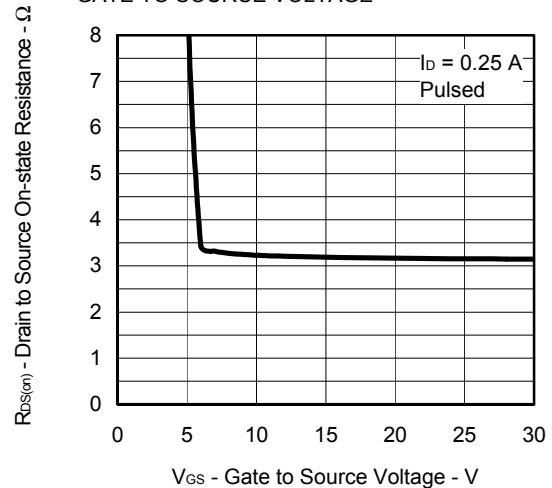
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



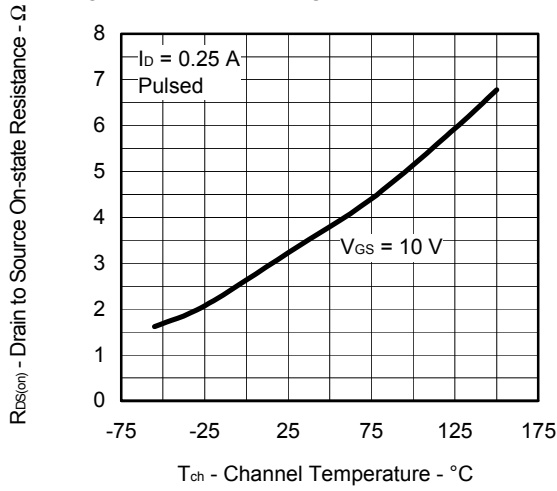
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



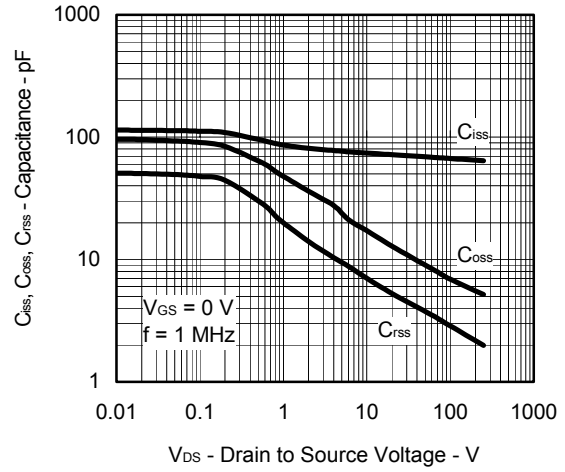
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



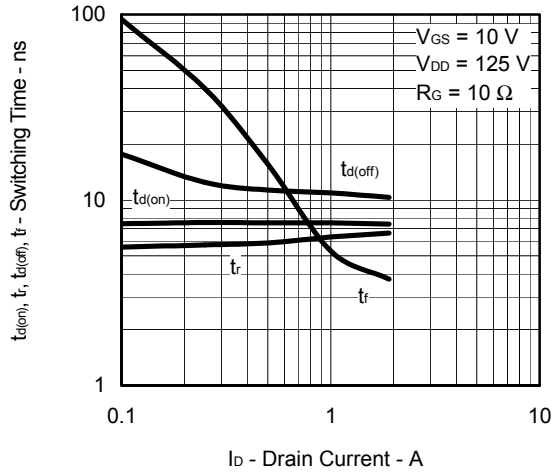
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



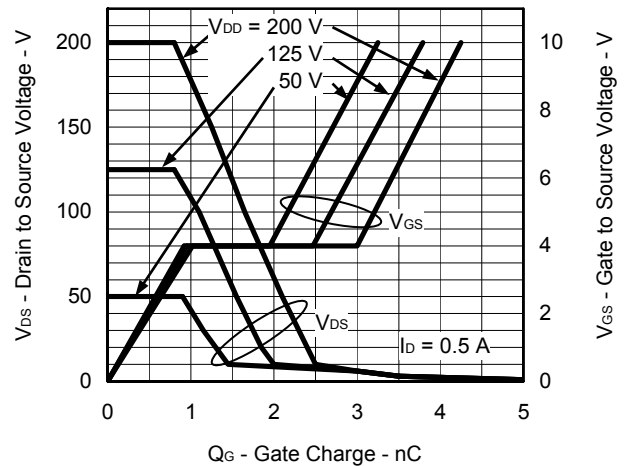
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



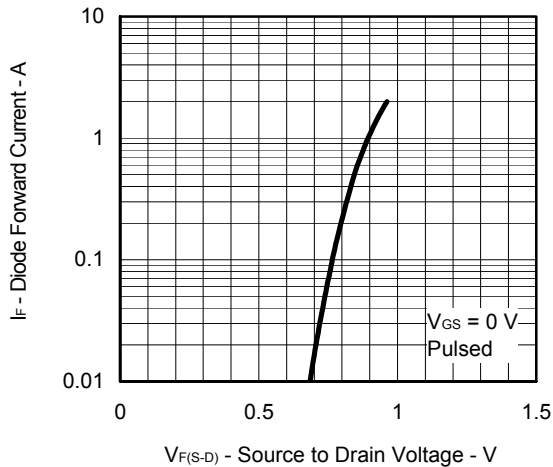
SWITCHING CHARACTERISTICS



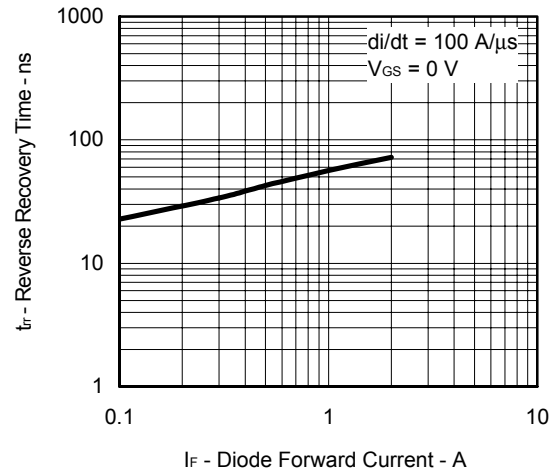
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



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